

2023.7.25 News Release

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Received large orders for “Wafer Handling System“ for 2.5D/3D Stacking Packages and Fan-Out packages

We, AIMECHATEC, Ltd. (Head Office: Koyodai, Ryugasaki-shi, Ibaraki-pref. President: Isao Abe) are pleased to announce that we additionally received a new large order for “Wafer Handling System” from a global OSAT (Outsourced Semiconductor Assembly and Test) company.

According to the needs and growths in 5G, IoT, AI, and autonomous driving markets, 2.5D/3D Stacking and Fan-out semiconductor package demand remains strong, and further thinning and stacking technologies are required.

Our wafer handling system equipment is one of the important processes for thinning and stacking. Our long-cultivated wafer temporary bonding technology with support glass to support wafer thinning down and related process. After that, glass debonding and cleaning for thinned wafer. So called Wafer Handling System (WHS). We have been proposing the high-performance wafer handling system equipment by combining our manufacturing capabilities. As a result, a global OSAT company obtained good evaluation result and they placed this large order. Currently, we have received inquiries from a large number of semiconductor package manufacturing companies, and they are considering adopting our equipment that can improve the yield rate.

We will continue to contribute to the society by improving convenient and affluent lifestyle through our technological innovations for manufacturing processes. Your continued kind support to our company is sincerely appreciated.

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